4.8mm Single-Level Circuit Board Indicator

Part Number: WP73JB/SGDA Super Bright Green

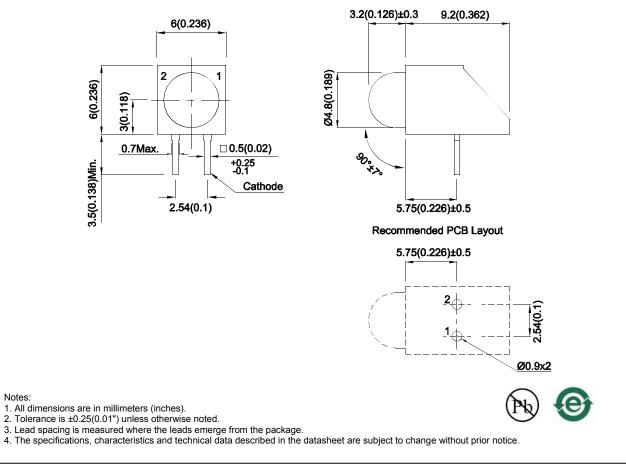
Features

- Pre-trimmed leads for pc board mounting
- Black case enhances contrast ratio
- High reliability life measured in years
- Housing UL rating: 94V-0
- Housing material: type 66 nylon
- RoHS compliant

Description

The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions



SPEC NO: DSAO7754 APPROVED: Wynec REV NO: V.2B CHECKED: Allen Liu DATE: DEC/09/2016 DRAWN: L.T.Zhang PAGE: 1 OF 5 ERP: 1102002067

Selection Guide

Selection Guide					
Part No.	Emitting Color (Material)	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
WP73JB/SGDA	Super Bright Green (GaP)	Green Diffused	12	55	40°

Notes:

01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity / luminous Flux: +/-15%.
Luminous intensity value is traceable to CIE127-2007 standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Green	565		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Green	568		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Green	30		nm	IF=20mA
С	Capacitance	Super Bright Green	15		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	Super Bright Green	2.2	2.5	V	I⊧=20mA
lr	Reverse Current	Super Bright Green		10	uA	VR = 5V

Notes:

1. Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V. 3. Wavelength value is traceable to CIE127-2007 standards.

4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Absolute Maximum Ratings at TA=25°C

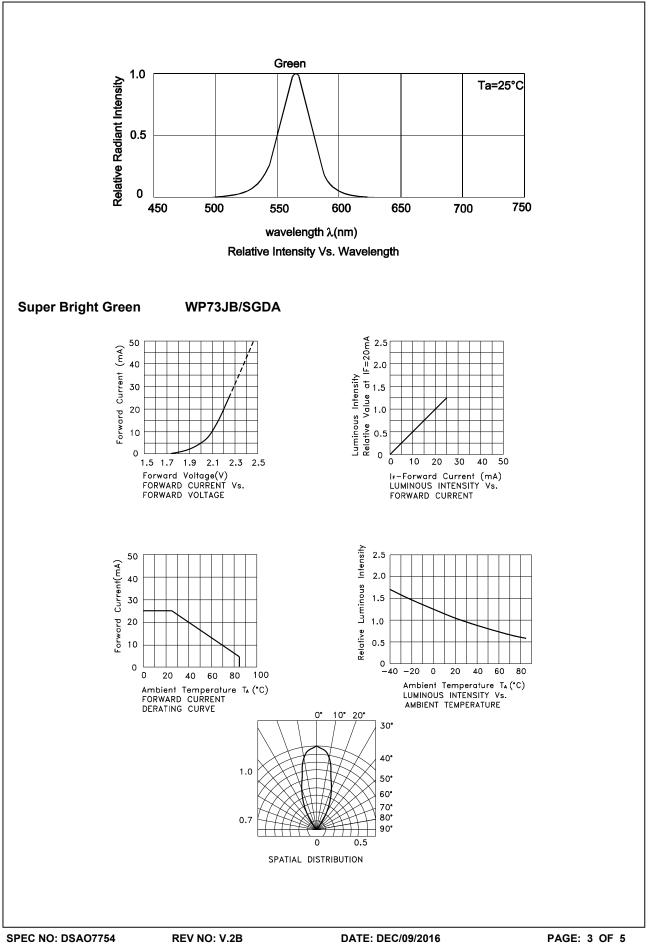
Parameter	Values	Units		
Power dissipation	62.5	mW		
DC Forward Current	25	mA		
Peak Forward Current [1]	140	mA		
Reverse Voltage	5	V		
Operating/Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [2]	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds			

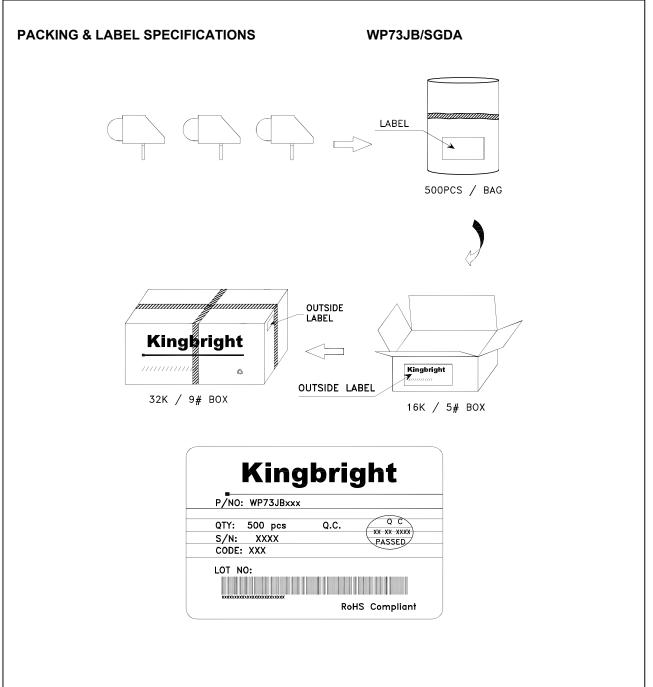
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. 2mm below package base.

Smm below package base.
Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.





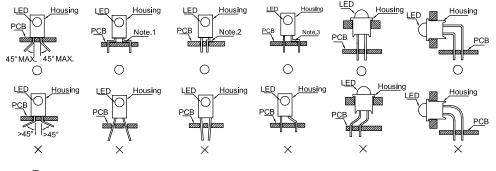
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DATE: DEC/09/2016 DRAWN: L.T.Zhang

PRECAUTIONS

- 1. Storage conditions:
 - a.Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.
 - b.LEDs should be stored with temperature \leq 30°C and relative humidity < 60%.
 - c.Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (+10/-0) hours at 85 ~ 100°C.
- 2. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



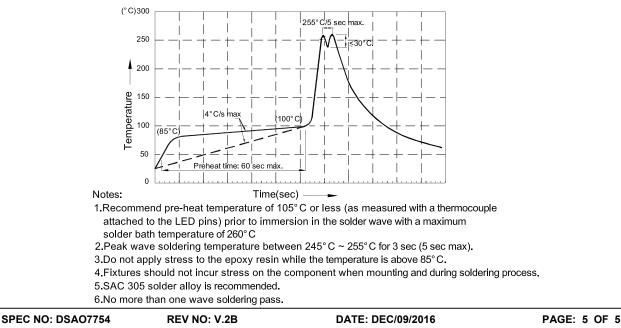
" () " Correct mounting method " imes " Incorrect mounting method

Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

3. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- 4. The tip of the soldering iron should never touch the lens epoxy.
- 5. Through-hole LEDs are incompatible with reflow soldering.
- 6. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 7. Recommended Wave Soldering Profiles:



CHECKED: Allen Liu

DRAWN: L.T.Zhang

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